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PATENT

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September 5, 2002  
Date

Denise Sheridan for  
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9/20/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant	: Vishnu K. Agarwal	Attorney Docket No.:	501082.04 (98-0616.03)
Serial No.	: 09/652,993	Group Art Unit	: 2815
Filed	: August 31, 2000	Examiner	: Jose R. Diaz
Title	: DEVICE AND METHOD FOR PROTECTING AGAINST OXIDATION OF A CONDUCTIVE LAYER IN SAID DEVICE		

Box Non-Fee Amendment  
Commissioner of Patents  
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Specification:

Please replace the paragraph beginning at page 8, line 4, with the following rewritten paragraph:

--Still other gases include diborane ( $B_2H_6$ ); phosphine ( $PH_3$ ); and carbon-silicon compounds such as methylsilane ( $CH_3SiH_3$ ) and hexamethyldisilane ( $(CH_3)_3Si-Si(CH_3)_3$ ); and hexamethyldisilazane (HMDS). Additional alternate embodiments of the current invention use hydrazine ( $N_2H_4$ ), monomethylhydrazine, carbon tetrafluoride ( $CF_4$ ),  $CHF_3$ ,  $HCl$ , and boron trichloride ( $BCl_3$ ), which are also useful in passivating dielectrics, as addressed in copending application 09/114,847, now issued as U.S. Patent No. 6,201,276 B1. Also included are mixtures of any of the gases or types of gases described above. Exemplary non-plasma process parameters using these other gases include a flow rate of about 2 sccm to about 400 sccm for

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